

Appl. No. : 09/844,959
Filed : April 27, 2001

AMENDMENTS TO THE CLAIMS

1-10. (Cancelled)

11. (Previously presented) An integrated circuit comprising an interconnect structure, said interconnect structure comprising a dielectric layer, said dielectric layer comprising at least a portion of a hard mask layer, the hard mask layer comprising a patterned organic polymer film wherein a portion of the patterned organic polymer film is fluorinated.

12. (Previously presented) The integrated circuit as recited in Claim 11, wherein the patterned organic polymer film is a patterned low-K organic polymer film.

13. (Previously presented) The integrated circuit as recited in Claim 11, wherein the patterned organic polymer film comprises a surface and an interior, wherein the surface comprises a fluorinated portion and the interior comprises a non-fluorinated portion.

14. (Previously presented) The integrated circuit as recited in Claim 13, wherein a K value of the fluorinated portion is less than a K value of the non-fluorinated portion.
